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Part Number: [0736441004](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position C, 144 Circuits

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	No



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73644Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	

Stackable	No	Extraction Tool	0621001000
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		
Electrical			
Current - Maximum per Contact	1A		
Data Rate	1.0 Gbps		
Real Signals (per 25mm)	75		
Shielded	No		
Voltage - Maximum	250V AC		
Material Info			
Reference - Drawing Numbers			
Packaging Specification	PK-70873-0818		
Sales Drawing	SDA-73644-****		
HDM and High Density Metric are trademarks of Amphenol Corporation			

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.
7. PACKAGE PER PK-70873-0818.
8. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



2	D
1	J
MFG.	SH. REV.

PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

DIMENSIONS SHOWN (METRIC) INCH

UNLESS OTHERWISE SPECIFIED
TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± N/A	---
2 PLACE	± N/A	± 0.05
1 PLACE	---	± 0.10

DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	2 : 1

REVISIONS ONLY ON CAD SYSTEM

TITLE

SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION	SHEET NO. 1 OF 2	DATE 96/12/18
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MOLEX INCORPORATED LISLE, ILL. 60532	PART NO. SDA-73644-****	DIV. DA	SIZE B
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Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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